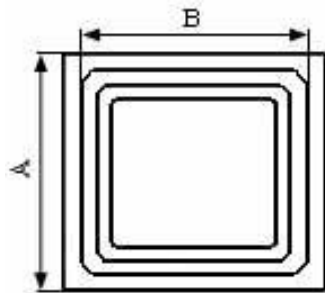


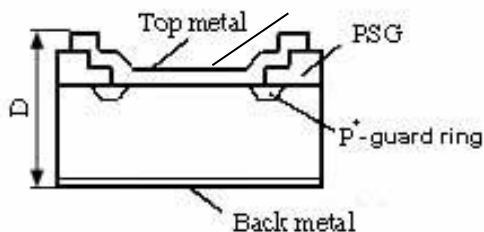


15A/30V. Die Size-123mil.

Electrical Characteristics	Symbol	Unit	Spec. limit	Die Sort
Breakdown Voltage @ $I_R=10mA$	V_{BR}	V	30	35
Average Rectified Forward Current	$I_{F(AV)}$	A	15,0	-
DC Forward Voltage @ 25°C, $I_F=15,0A$	V_F	V	0,49	0,47
Maximum Reverse Current @ 25°C, $V_R=35V$ @ 25°C, $V_R=30V$ @ 125°C, $V_R=30V$	I_R	mA	- 0,30 150	0,30 0,25 130
Peak Forward Surge Current 8,3ms single half sine-wave superimposed on rated load (JEDEC METHOD)	I_{FSM}	A	250	-
Peak Repetitive Reverse Surge Current @ 2,0µs, $f=1kHz.$, $T_J<150°C.$	I_{RRM}	A	5,0	
Electrostatic Discharge Voltage. JEDEC Method. ESD HBM. Contact.	ESD	kV	±8 (contact)	
Voltage Rate of Change	dV/dt	V/µS	10.000	
Operating Junction Temperature	T_J	°C	150	



DIM	ITEM	µm
A_x A_y	Wafer Form Die Size	3120
B_x B_y	Top Metal Size	2980
D	Thickness	300max.
Scribe line Width		80



Top metal:

- a) Al – for Wire Bonding;
- b) Al-Ni-Ag – for Soldering.

Backside metal: Ti-Ni-Ag.